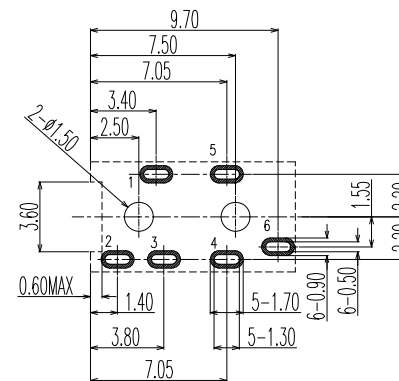
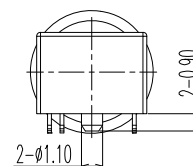
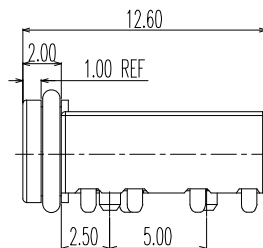
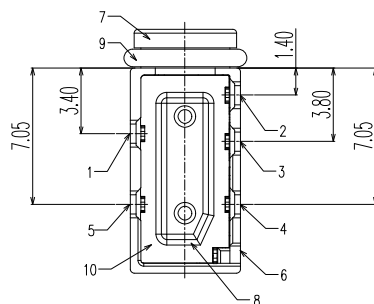
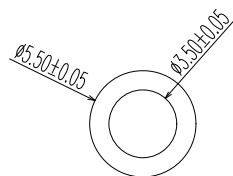
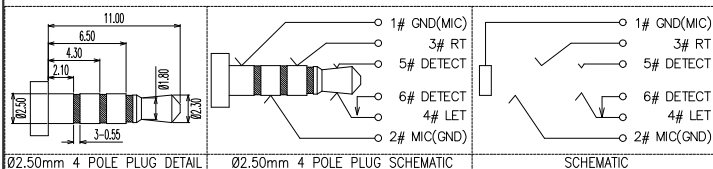


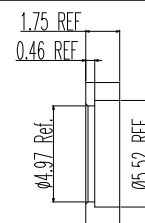
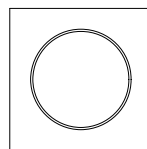
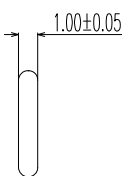
3D VIEW



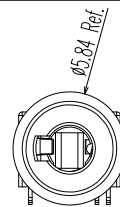
PCB LAYOUT (TOP VIEW)
TOLERANCE: ±0.05



WATERPROOF RING



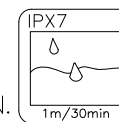
面板开孔参考尺寸



INSTALL WATERPROOF RING
(UNCOMPRESSED)

NOTES

1. CURRENT RATING: 1A.
2. CONTACT RESISTANCE: 100mΩ MAX.
3. INSULATION RESISTANCE: 100MΩ MIN.
4. DIELECTRIC WITHSTANDING: 500V AC MIN.
5. DURABILITY: 5000 CYCLES MIN.
6. CONNECTOR MATING FORCES: 3~30N.
7. CONNECTOR UNMATING FORCES: 3~30N.
8. OPERATING TEMPERATURE: -25°C TO +85°C.
9. WATERPROOF LEVEL: IP67



Not to install the waterproof ring shipment

10	GLUE	EPOXY	COLOR BLACK	1
9	WATERPROOF RING	SILICONE	COLOR BLACK	1
8	COVER	HIGH TEMPERATURE	COLOR BLACK	1
7	HOUSING	HIGH TEMPERATURE	COLOR BLACK	1
6	TERMINAL 6#	PHOSPHOR BRONZE	NICKEL UNDERPLATING OVERALL, GOLD FLASH PLATING ON THE SOLDER & CONTACT AREA	1
5	TERMINAL 5#	STAINLESS STEEL	NICKEL UNDERPLATING OVERALL, GOLD FLASH PLATING ON THE SOLDER & CONTACT AREA	1
4	TERMINAL 4#	STAINLESS STEEL	NICKEL UNDERPLATING OVERALL, GOLD FLASH PLATING ON THE SOLDER & CONTACT AREA	1
3	TERMINAL 3#	PHOSPHOR BRONZE	NICKEL UNDERPLATING OVERALL, GOLD FLASH PLATING ON THE SOLDER & CONTACT AREA	1
2	TERMINAL 2#	PHOSPHOR BRONZE	NICKEL UNDERPLATING OVERALL, GOLD FLASH PLATING ON THE SOLDER & CONTACT AREA	1
1	TERMINAL 1#	STAINLESS STEEL	NICKEL UNDERPLATING OVERALL, GOLD FLASH PLATING ON THE SOLDER & CONTACT AREA	1
NO.	DESCRIPTION	MATERIAL	REMARKS	QTY

Guangdong Tengjun Electronic Technology Co., Ltd

DRAWING NO:

JA06-BPD002-A

REV A0

SIZE: A4



PART NAME

WATERPROOF Ø2.5 PHONE JACK

PART NO.

JA06-BPD002-A

TOLERANCE UNLESS
OTHERWISE SPECIFIED:

X ±0.2
X.X ±0.15
X.XX ±0.10
X.XXX ±0.050

DRAWING:

Li

DATE:

2019.11.12

CHECK:

Chen

DATE:

2019.11.12

APPROVAL:

Yuan

DATE:

2019.11.12

SHEET

1/1